# **PRODUCT SPECIFICATION**

# 1.06" TFT LCD MODULE MODEL: YDP LCD TN 106 S



- $< \diamond >$  Preliminary Specification
- < <> Finally Specification

CUSTOMER'S APPROVAL						
CUSTOMER :						
SIGNATURE: DATE:						

APPROVED	РМ	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
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# knitter-switch

# **Revision History**

Revision	Date	Originator	Detail	Remarks
1.0	2024.07.25	DFG	Initial Release	

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### 1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver IC and a backlight unit.

# 2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	1.06"	
LCD type	TN TFT	
Display Mode	Transmissive /Normally White	
Resolution	96 RGB x 160	Pixels
View Direction	TBD	Best Image
Module Outline	16.12 (H) x 29.76 (V) x 1.69(T) (Note1)	mm
Active Area	13.824 (H) x 23.04 (V)	mm
Pixel Size	144(H) x 144 (V)	um
Pixel Arrangement	RGB Vertical Stripe	
Display Colors	262K	
Interface	4 Line SPI	
Driver IC	GC9107	-
With or without touch panel	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	٥C
Weight	(1.3)	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

# 3. Absolute Maximum Ratings

			V <sub>SS</sub> =0 <sup>v</sup>	V, Ta=25⁰C
Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	-0.3	4.6	V
Logic Input Voltage	VIN	-0.3	VDD+0.3	V
Storage temperature	Tstg	-30	+80	°C
Operating temperature	Тор	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around  $-10^{\circ}$ C, and the back ground will become darker at high temperature operating.

# 4. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage	VDD	2.5	2.8	3.3	V
Operating Current for V <sub>DD</sub>	I <sub>DD</sub>	-	(2)	(3)	mA

# 5. Backlight Characteristic

### 5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Backlight Voltage	VLED	Ta=25 °C, I <sub>F</sub> =20mA/ LED	-	3.0	-	V
Backlight Current	ILED	Ta=25 °C, V⊧=3.0V/ LED	-	20	-	mA
Power dissipation	PD	-	-	60	-	mW
Uniformity	Avg	-	-	(80)	-	%
LED working life(25℃)	-	-		TBD	-	Hrs
Drive method	Constant current					
LED Configuration		1 WHITI	ELED			

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25 $\pm$ 2 °C,60%RH $\pm$ 5%, I<sub>F</sub>=20mA/LED.

### 5.2. Backlighting circuit



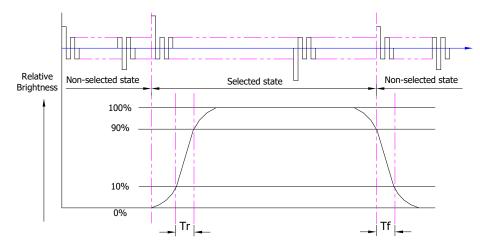
# 6. Optical Characteristics

### 6.1. Optical Characteristics

						Ta=	=25°C, VDD	)=2.8V
	ltem		Symbol Condition	Condition	Specification			Unit
le)	item			Min.	Тур.	Max.	Unit	
	Luminar	nce on						
	TFT( $I_f$ =20mA/LED)		Lv	Normally	320	400	-	cd/m²
ode	Contrast ratio	o(See 6.3)	CR	viewing angle θx = φy =0°	-	800	-	
Backlight On (Transmissive Mode)	Response time (See 6.2)		TR+TF		-	30	40	ms
nis	Chromoticity	$\frac{\text{Red}}{\text{Hromaticity}} \frac{X_{\text{R}}}{Y_{\text{R}}}$	XR		-	TBD	-	
usu			YR		-	TBD	-	
Tra			XG		-	TBD	-	
) u	Transmissive			-	TBD	-		
t U	(See 6.5)	Blue	Хв		-	TBD	-	
(lig	(000 0.0)	Dide	Υв		-	TBD	-	
ack		White	Xw		-	TBD	-	
6		White	Yw		-	TBD	-	
	Viewing	Horizontal	θx+		-	TBD	-	
	Angle		θx-	Center CR≥10	-	TBD	-	Deg.
	(See 6.4)	Vertical	φΥ+		-	TBD	-	Deg.
	(000 0.4)	ventical	φΥ-		-	TBD	-	

### 6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

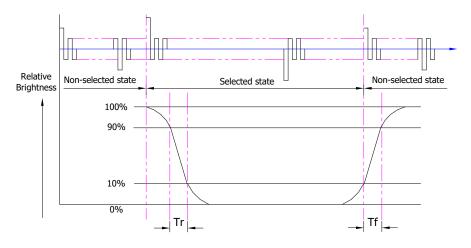


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

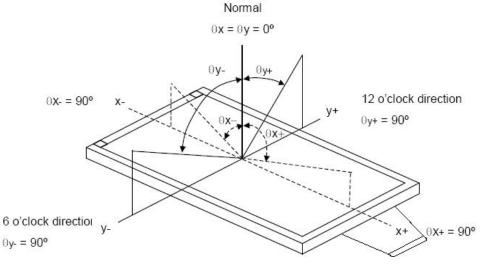
#### 6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test pattern	A: All Pixels white
Test pattern	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

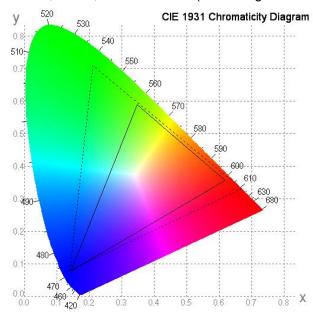
#### 6.4. Definition of Viewing Angles



Measuring machine: LCD-5100 or EQUI

### 6.5. Definition of Color Appearance

R, G, B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100% Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

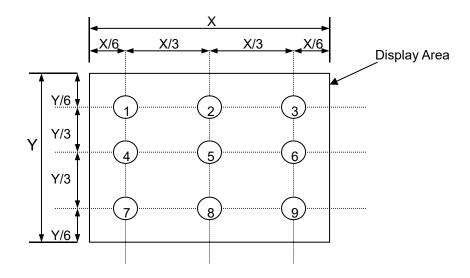


### 6.6. Definition of Surface Luminance, Uniformity and Transmittance

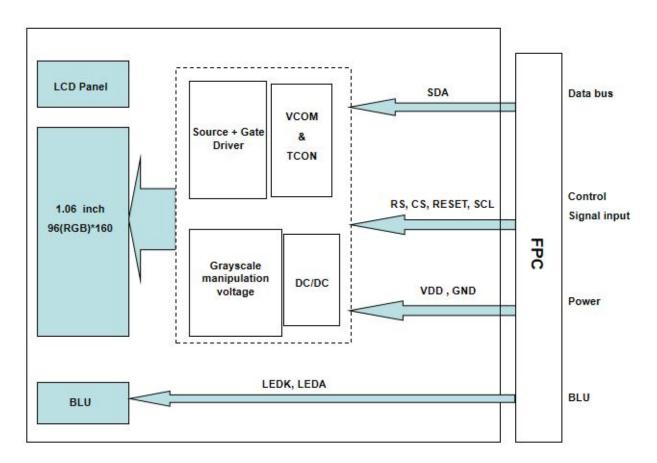
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance: L<sub>V</sub> = average (L<sub>P1</sub>:L<sub>P9</sub>)
- 6.6.2. Uniformity = Minimal (L<sub>P1</sub>:L<sub>P9</sub>) / Maximal (L<sub>P1</sub>:L<sub>P9</sub>) \* 100%
- 6.6.3. Transmittance =  $L_V$  on LCD /  $L_V$  on Backlight \* 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



# 8. Interface Pins Definition

No.	Symbol	Function	Remark
1	NC	No connection	
2	NC	No connection	
3	SDA	SPI interface input/output pin	
4	SCL	This pin is used to be serial interface clock	
5	RS	Display data/command selection pin in 4-line serial interface	
6	RESET	This signal will reset the device, Signal is active low	
7	CS	Chip selection pin. Low enable, High disable.	
8	GND	Ground.	
9	NC	No connection	
10	VDD	Power supply	
11	LEDK	LED Cathode	
12	LEDA	LED Anode	
13	GND	Ground	

# 9. AC Characteristics

TBD

### 10. Quality Assurance

### 10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

#### 10.2. Standard for Quality Test

- 10.2.1. Sampling Plan:
  - GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

### 10.3.Nonconforming Analysis & Disposition

- 10.3.1. Nonconforming analysis:
  - 10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
  - 10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
  - 10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.
- 10.3.2. Disposition of nonconforming:
  - 10.3.2.1. Non-conforming product over PPM level will be replaced.
  - 10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

### 10.4.Agreement Items

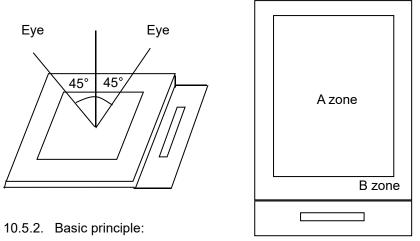
Shall negotiate with customer if the following situation occurs:

- 10.4.1. There is any discrepancy in standard of quality assurance.
- 10.4.2. Additional requirement to be added in product specification.
- 10.4.3. Any other special problem.

#### 10.5. Standard of the Product Visual Inspection

- 10.5.1. Appearance inspection:
  - 10.5.1.1. The inspection must be under illumination about 1000 1500 lx, and the distance of view must be at 30cm ± 2cm.
  - 10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.10.5.2.2. New item must be added on time when it is necessary.

10.6.Inspection Specification

No.	ltem	Criteria (Unit: mm)					
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	$\phi = (a + b)/2$ Distance between 2 of	defects :	Size	o≤0.15 o≤0.25 <φ al	lgı 2 no φ≤	c. Qty nore 2 1 0 include 0.10
02	Electrical Defect (Minor defect)	Bright dot Dark dot Total dot Mura Remark: 1. Bright dot caused	Not v	ay Area 0 I≤2 I≤2 risible throu		) ≨2 ≨2 filters.	Note1 Note 2 to item 1.

03	Black and White line Scratch Foreign material (Line type) (Minor defect)	Length I $L \leq 2.5$ $L \leq 2.5$ I Distance between 2	W Width W $\leq 0.03$ $0.03 < W \leq 0.05$ $0.05 < W \leq 0.10$ 0.1 < W Total 2 defects should more that h the back of the display a		tches
04	Glass Crack (Minor defect)	Crack is potential to	enlarge, any type is not a	allowed.	

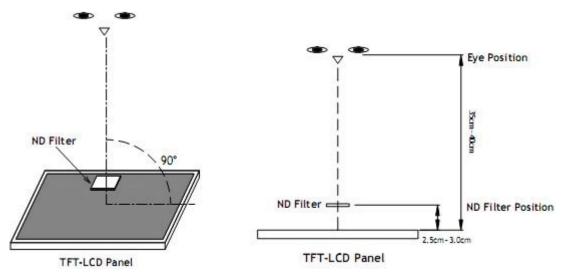
05	Glass Chipping Pad Area: (Minor defect)	
		Length and Width Acc. Qty
		c > 3.0, b< 1.0 1
		c< 3.0, b< 1.0 3
		a <glass td="" thickness<=""></glass>
	b g c c	

	Glass Chipping Rear of Pad Area: (Minor defect)		
06		Length and Width	Acc. Qty
		c > 3.0, b< 1.0	1
		c< 3.0, b< 1.0	2
		c< 3.0, b< 0.5	4
	to the second se	a <glass td="" thic<=""><td>kness</td></glass>	kness
	y ya		
	Glass Chipping Except Pad Area: (Minor defect)		
	~	Length and Width	Acc. Qty
		c > 3.0, b< 1.0	1
07		c< 3.0, b< 1.0	2
		c< 3.0, b< 0.5	4
	- Contraction of the second se	a <glass td="" thic<=""><td>kness</td></glass>	kness
	a↓_		
	Glass Corner Chipping: (Minor defect)		
		Length and Width	Acc. Qty
		c < 3.0, b< 3.0	Ignore
08	b a c c	a <glass td="" thic<=""><td>kness</td></glass>	kness
	Glass Burr:		
	(Minor defect)	Length	Acc. Qty
		F < 1.0	
09		Glass burr don't affect as dimension.	Ignore semble and module

FPC Defect: (Minor defect) w		<ul> <li>10.1 Dent, pinhole width a<w 3.<="" li=""> <li>(w: circuitry width.)</li> <li>10.2 Open circuit is unacceptable.</li> <li>10.3 No oxidation, contamination and distortion.</li> </w></li></ul>		nd distortion.
Bubble on Polarizer (Minor defect)		Diameter         φ≤0.20         0.20 <φ≤0.30	Acc. Qty Ignore 4 1 None	
Dent on Polarizer (Minor defect)		Diameter φ≤0.20 0.20 <φ≤0.30 0.30 <φ≤0.50 0.50 < φ	Acc. Qty Ignore 4 1 None	
Bezel	13.1 No rust, distortion on the Bezel. 13.2 No visible fingerprints, stains or other contamination.			
PCB	<ul> <li>14.1 No distortion or contamination on PCB terminals.</li> <li>14.2 All components on PCB must same as documented on the BOM/component layout.</li> <li>14.3 Follow IPC-A-600F.</li> </ul>			
Soldering	Follow IPC-A-610C standard			
Electrical Defect (Major defect)	The below defects must be rejected. 16.1 Missing vertical / horizontal segment, 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch Panel no function			
	(Minor defect) W J Carlor Bubble on Polarizer (Minor defect) Dent on Polarizer (Minor defect) Bezel PCB Soldering Electrical Defect	(Minor defect)         w	(Minor defect)10.1 Dent, pinhole f (w: circuitry width.) 10.2 Open circuit is 10.3 No oxidation, or 10.3 No oxidation, or 10.4 Dent, pinhole f (w: circuitry width.) 10.2 Open circuit is 10.3 No oxidation, or 10.3 No oxidation, or 10.4 Dent, pinhole f (w: circuitry width.) 10.2 Open circuit is 10.3 No oxidation, or 10.20 open circuit is 10.20 open circuit is 10.3 No oxidation, or 10.20 open circuit is 10.20 open	(Minor defect)10.1 Dent, pinhole width a <w 3.<br=""></w> (w: circuitry width.)10.1 Dent, pinhole width a <w 3.<br=""></w> (w: circuitry width.)10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination atDiameterMinor defect)Dent on Polarizer (Minor defect)Defect (Major defect)PCBElectrical Defect (Major defect)Electrical Defect (Major defect)Ch on Statkinght. (6.4 Current exceeds product specifications. (6.5 LCD viewing angle defect. (6.6 No Backlight. (6.6 No Backlight. (6.7 Dark Backlight.

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is  $350 \text{ mm} \pm 50 \text{ mm}$ .

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is  $350 \text{ mm} \pm 50 \text{ mm}$ .

**Note2:** Mura on display which appears darker / brighter against background brightness on parts of display area.

# 11. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50℃, 85%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-20℃, 60min~70℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: $\pm$ 4KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.2 -2018
		Contact: $\pm$ 2KV 150pF/330 $\Omega$ 5 times		
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.7- 2018

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

### 12. Precautions and Warranty

### 12.1.Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

### 12.2.Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

### 12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

### 12.4. Metal Pin (Apply to Products with Metal Pins)

- 12.4.1. Pins of LCD and Backlight
  - 12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering
  - 12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

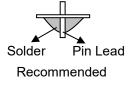
Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20℃

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting





- 12.4.2. Pins of EL
  - 12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.
  - 12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.
  - 12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

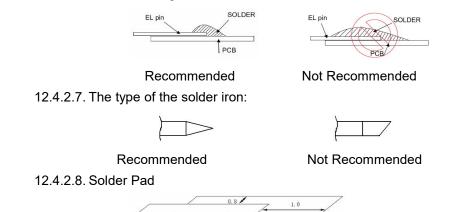
Recommended Solder Temperature: 270~290°C

Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

- 12.4.2.4. No horizontal press on the EL leads during soldering.
- 12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting



### 12.5.Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it may develop image sticking due to the TFT structure.

### 12.6.Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

#### **12.7.Limited Warranty**

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

# 13. Packaging

TBD

# 14. Outline Drawing

